

MULTIDIMENSIONAL ULTRASONIC TRANSDUCER ARRAYS

Abstract of the disclosure:

5           A two dimensional ultrasonic transducer array stack  
is described which has a backing block of acoustically  
absorbent material formed of alternating plates of backing  
material and flex circuits adhesively bonded together.  
The thickness of the plates establishes the elevational  
10       dimension between the flex circuits and corresponds to the  
elevational pitch of the two dimensional array. The  
backing block may also be formed by photoetching  
conductive traces directly on the plates of backing  
material, which are then adhesively bonded together to  
15       form the backing block.

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